

LINEAR TECHNOLOGY MATERIALS DECLARATION

LT3680EDD#TRPBF

(Engineering Calculation)

DFN 3mm X 3mm Exp. Pad

(printed on: 2014-01-20 00:43:11)

TOTAL MASS (g): 0.023808

| COMPONENT MATERIAL | VENDOR/INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL Pkg. | | |
|--------------------------------|----------------------------------|--------------------------|-------------------------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.001589 | 1000000 | 66741.2578125 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.009711 | 975000 | 40781.90625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000239 | 24000 | 10038.4892578 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000003 | 300 | 126.006156921 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000007 | 700 | 294.014141262 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead Frame Total: | | | | 0.009960 | 1000000 | 418340.4375 |
| | | Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 |
| Exter. Plating Sn | 7440-31-5 | | | 0.000455 | 1000000 | 19126.1660156 | | |
| External Plating Total: | | | | | | 0.000455 | 1000000 | 19126.1660156 |
| Inter. Plating Ni | 7440-02-0 | | | 0.000000 | 0 | 0 | | |
| Inter. Plating Ag | 7440-22-4 | | | 0.000225 | 1000000 | 9450.4609375 | | |
| Internal Plating Total: | | | | | | 0.000225 | 1000000 | 9450.4609375 |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000774 | 750000 | 32509.5878906 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000258 | 250000 | 10836.528203 | | |
| | | Die Attach Total: | | | | 0.001032 | 1000000 | 43346.1132812 |
| | | Encapsulation | MULTIAROMATIC RESIN BOND FREE | Resin (EP) | | 0.001162 | 130000 | 57206.7890625 |
| Bromine (Br) | 40093-93-8 | | | 0.000000 | 0 | 0 | | |
| Silica (SiO2) | 60676-86-0 | | | 0.009013 | 860000 | 378564.46875 | | |
| Antimony Trioxide (Sb2O3) | 1309-64-4 | | | 0.000000 | 0 | 0 | | |
| Metal Hydroxide | | | | 0.000000 | 0 | 0 | | |
| Carbon Black (C) | 1333-86-4 | | | 0.000105 | 10000 | 4410.21533203 | | |
| Encapsulation Total: | | | | | | 0.010480 | 1000000 | 440181.46875 |
| Bond Wire Estimated | AFW/TANAKA/Kn | Gold (Au) | 7440-57-5 | 0.000067 | 1000000 | 284.13745117 | | |

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